MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



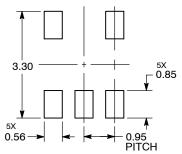


SOT-23 5-LEAD CASE 1212-01 **ISSUE A**

DATE 28 JAN 2011

В Α 0.05 S 5X **b** L1 ⊕ 0.10 M C B S A S

RECOMMENDED **SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSIONS: MILLIMETERS.
 3. DATUM C IS THE SEATING PLANE.

	MILLIMETERS		
DIM	MIN	MAX	
Α		1.45	
A1	0.00	0.10	
A2	1.00	1.30	
b	0.30	0.50	
C	0.10	0.25	
D	2.70	3.10	
Е	2.50	3.10	
E1	1.50	1.80	
е	0.95 BSC		
L	0.20		
L1	0.45	0.75	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.